

JOM Call for papers

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Manuscript Deadline: *June 1, 2019*

The Electronic Packaging and Interconnection Materials Committee is seeking papers on the topic of *Progress with Lead-Free Solders*

Pb-free solders are now in widespread use and can out-perform Pb-based materials in many applications. Despite this success, there is an ongoing need to develop next-generation interconnection materials for smaller joints that can operate in more extreme environments and that are more reliable. This topic covers recent advances in solder alloy design for harsh environments, new interconnection materials and bonding technologies, and advances in the understanding of electronics reliability.

Original research papers should be 3,000-6,000 words with up to 8 figures maximum; review papers should be 6,000-10,000 words with up to 15 figures maximum.

Detailed author instructions are available at:
<http://www.tms.org/AuthorTools/>

Guest Editors for the *JOM* topic are Chris Gourlay and Babak Arfaei:
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If you are interested in submitting a paper, upload your manuscript at
<https://www.editorialmanager.com/jomj/>

Please note that all submissions will be subject to peer review. Submission does not guarantee acceptance.

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